

## Product Change Notification - KSRA-06VYDO430

**Date:** 15 Jun 2017  
**Product Category:** 8-bit PIC Microcontrollers  
**Notification subject:** CCB 2986: Initial Notice: Qualification of CuPdAu bond wire for selected products of 250K and 290K wafer technology available in 28L UQFN package at NSEB assembly site.  
**Notification text:** **PCN Status:**  
 Initial notification.

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products of 250K and 290K wafer technology available in 28L UQFN package at NSEB assembly Site.

**Pre Change:**

Using gold (Au) bond wire

**Post Change:**

Using palladium coated copper with gold flash (CuPdAu) bond wire

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	NSEB Assembly Site	NSEB Assembly Site
<b>Wire material</b>	Au Wire	CuPdAu Wire
<b>Die attach material</b>	8600	8600
<b>Molding compound material</b>	G700LTD	G700LTD
<b>Lead frame material</b>	EFTEC64T	EFTEC64T

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at NSEB assembly site.

**Change Implementation Status:**

In Progress

**Estimated Qualification Completion Date:**

November 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

	June 2017					-->	November 2017				
Workweek	22	23	24	25	26		44	45	46	47	48
Initial PCN Issue Date			X								
Qual Report Availability										X	
Final PCN Issue Date										X	

**Method to Identify Change:**

Traceability code

**Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan.

**Revision History:**

**June 15, 2017:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

- [PCN\\_KSRA-06VYDO430\\_Affected CPN.pdf](#)
- [PCN\\_KSRA-06VYDO430\\_Qual Plan.pdf](#)
- [PCN\\_KSRA-06VYDO430\\_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

<b>PCN_KSRA-06VYDO430</b>
<b>CATALOG_PART_NBR</b>
PIC16F15354-E/MV
PIC16F15354-I/MV
PIC16F15354T-I/MV
PIC16F15355-E/MV
PIC16F15355-I/MV
PIC16F15355T-I/MV
PIC16F15356-E/MV
PIC16F15356-I/MV
PIC16F15356T-I/MV
PIC16F18854-E/MV
PIC16F18854-I/MV
PIC16F18854T-I/MV
PIC16F18855-E/MV
PIC16F18855-I/MV
PIC16F18855T-E/MV
PIC16F18855T-I/MV
PIC16F18856-E/MV
PIC16F18856-I/MV
PIC16F18856T-I/MV
PIC16LF15354-E/MV
PIC16LF15354-I/MV
PIC16LF15354T-I/MV
PIC16LF15355-E/MV
PIC16LF15355-I/MV
PIC16LF15355T-I/MV
PIC16LF15356-E/MV
PIC16LF15356-I/MV
PIC16LF15356T-I/MV
PIC16LF18854-E/MV
PIC16LF18854-I/MV
PIC16LF18854T-I/MV
PIC16LF18855-E/MV
PIC16LF18855-I/MV
PIC16LF18855T-I/MV
PIC16LF18856-E/MV
PIC16LF18856-I/MV
PIC16LF18856T-I/MV
PIC18F24K40-E/MV
PIC18F24K40-I/MV
PIC18F24K40T-I/MV
PIC18F24K42-E/MV
PIC18F24K42-I/MV
PIC18F24K42T-I/MV

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Affected Catalog Part Numbers (CPN)

<b>PCN_KSRA-06VYDO430</b>
<b>CATALOG_PART_NBR</b>
PIC18F25K40-E/MV
PIC18F25K40-I/MV
PIC18F25K40T-I/MV
PIC18F25K42-E/MV
PIC18F25K42-I/MV
PIC18F25K42T-I/MV
PIC18F26K40-E/MV
PIC18F26K40-I/MV
PIC18F26K40T-E/MV
PIC18F26K40T-I/MV
PIC18LF24K40-E/MV
PIC18LF24K40-I/MV
PIC18LF24K40T-I/MV
PIC18LF24K42-E/MV
PIC18LF24K42-I/MV
PIC18LF24K42T-I/MV
PIC18LF25K40-E/MV
PIC18LF25K40-I/MV
PIC18LF25K40T-I/MV
PIC18LF25K42-E/MV
PIC18LF25K42-I/MV
PIC18LF25K42T-I/MV
PIC18LF26K40-E/MV
PIC18LF26K40-I/MV
PIC18LF26K40T-I/MV